



***Earnings Call
September 1, 2022***

***Presented by:
Jacob Herschmann, CEO
Nava Ben-Yehuda, V.P. of Finance***

Overview - Microelectronics Reliability Testing

- Test and analysis of various mechanisms, which cause degradation and potential failures in semiconductor chips.
- Tests are performed on dedicated 'DUTs' (Devices Under Test)
- Test equipment (systems) controls temperature (up to 350° C), and uses current / voltage stimuli to accelerate degradation (from years - under normal operation - to hours, days, weeks).
- Testing performed using either 'PLR' (Package Level Reliability) or 'WLR' (Wafer Level Reliability)
- Test systems include many accurate current / voltage sources, high-accuracy data acquisition units, temperature-chambers, and complex control & data-analysis software.

MIRA: Cost effective Electromigration & Stress-migration

Infinity: High performance and versatility (HCD, TDDDB,...)

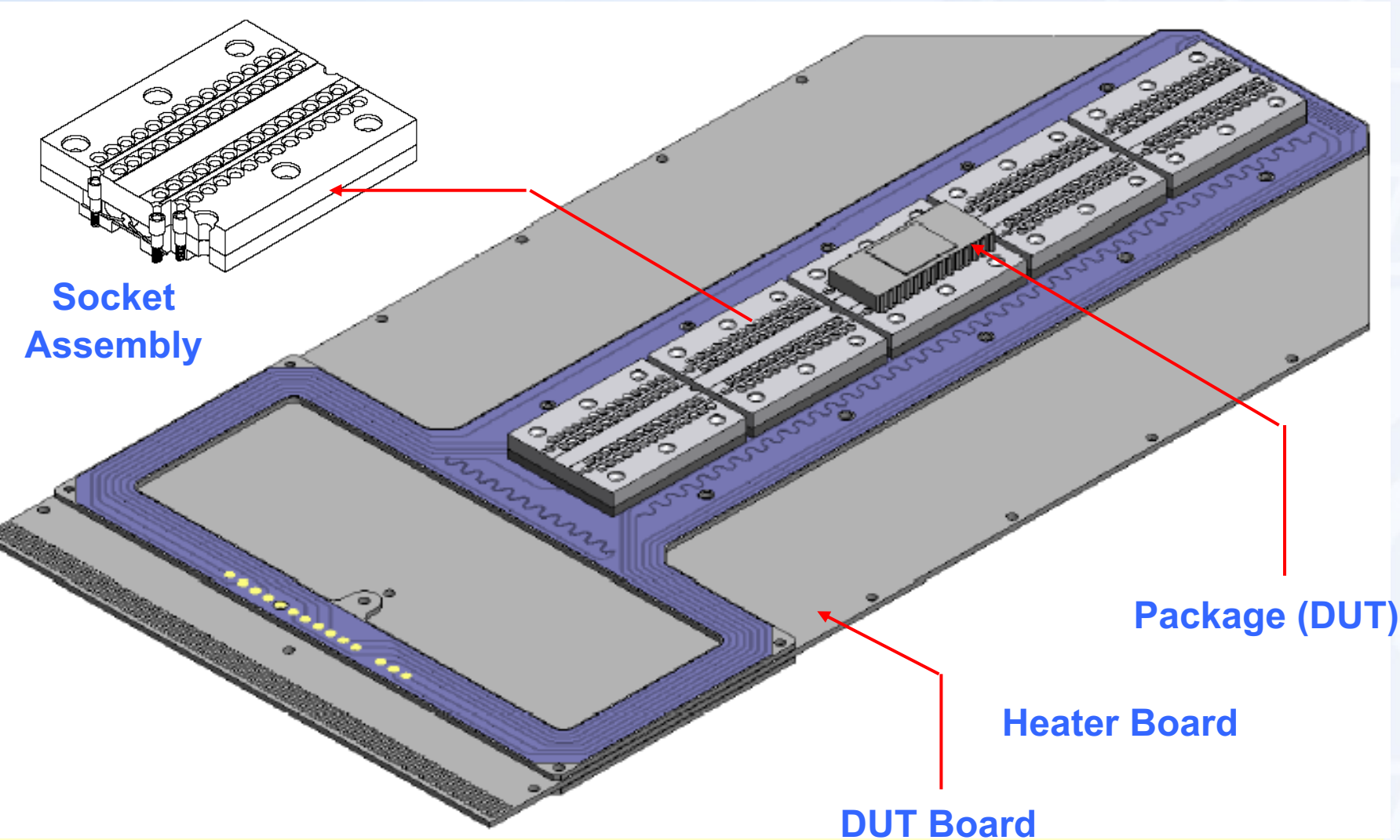
ACE: Pulsed (AC) applications

Probers: Multi-site, Semi-auto for Wafer - Level - Reliability

Accessories: Ovens, DUT Boards, Sockets, and Coolers.

Note: *The following examples present one specific product / application per product family.*

Mira-Package level Reliability



Mira Micro Oven System
480 DUT Capacity

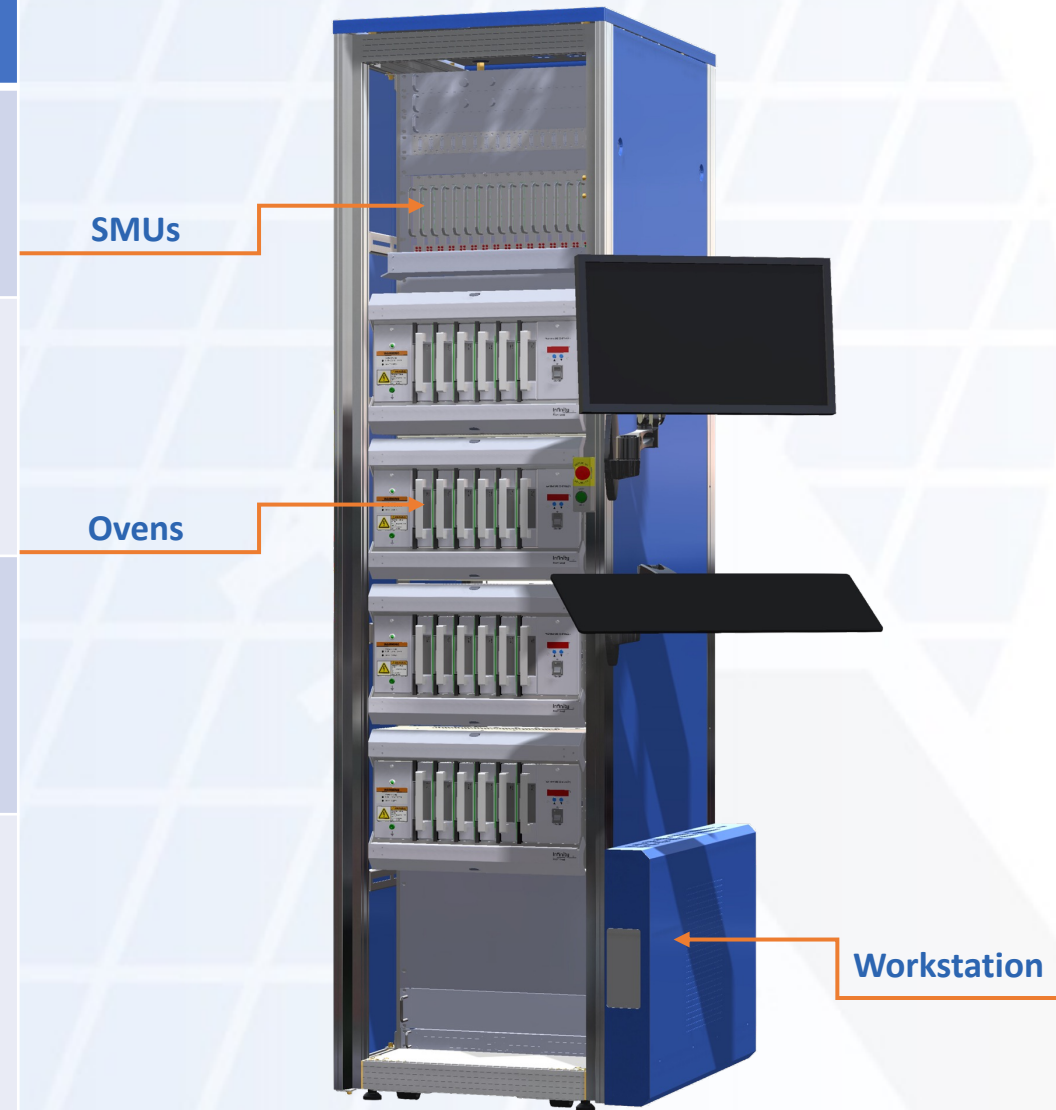


Testing the Future

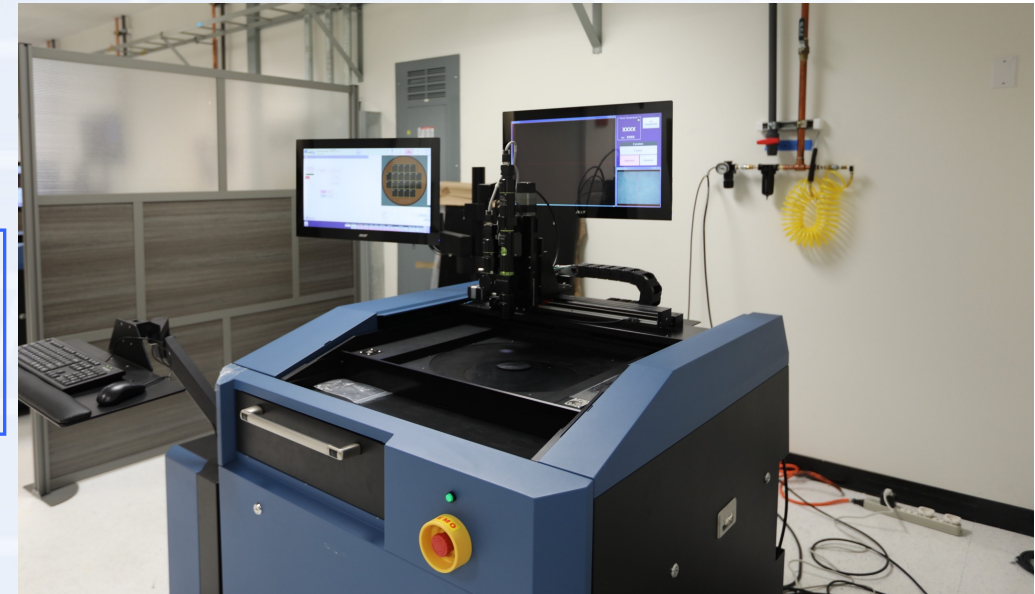
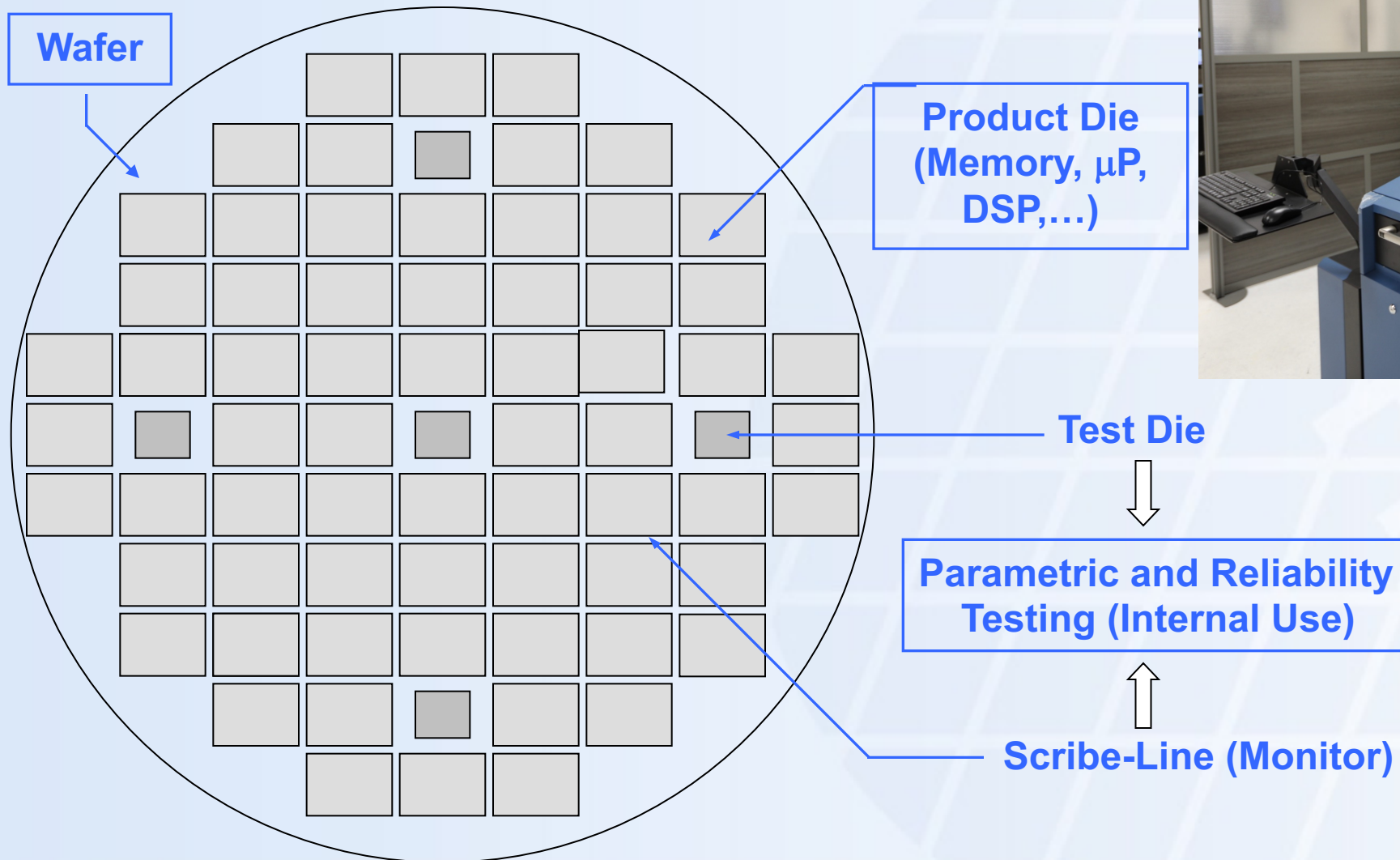
Infinity – Package level Reliability

Test Type	Device Being Tested and Failure Mode	End Product
TDDDB	Gate dielectrics of transistors or inter/intra-layer dielectrics insulating the interconnects of ICs. Failure is a destructive breakdown of the dielectric, causing a short circuit.	Nearly all electronic devices
HCI	MOSFET and bipolar junction transistors used for integrated circuits and discrete devices. A gradual degradation of parameters is expected, impacting performance and operation of the device.	Nearly all electronic devices
BTI	MOSFET devices, often PMOS devices subject to NBTI (Negative Bias Temperature Instability) stress. Gradual degradation is expected with both temporary and permanent components to the degradation.	Nearly all electronic devices
HTRB	MOSFET devices, often WBG devices like Gallium Nitride (GaN) and Silicon Carbide (SiC) used for high voltage and high frequency transistors. Failure is observed as gradual degradation of transistor parameters.	Electric Vehicles, Radar, Wireless Communication and Extreme Environments among many others.

Infinity Package Level System



Wafer level Reliability (WLR)



ACE SYSTEM

Electromigration effects on interconnects used under AC conditions have typically been approximated using “corrected” results from DC electromigration testing. However, the ever-increasing miniaturization of components and the need to question the traditional DC to AC correction factors have produced a growing demand for advanced testing tools and techniques that more closely simulate “real-world” degradation of interconnects used under AC conditions. To meet this demand, QualiTau has developed the ACE, an innovative pulsed electromigration system.



Testing the Future

Complementary Business Activity

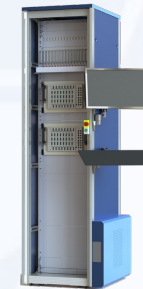
- **Customer support**
 - Service contracts
 - Ongoing service (by request)
- **Testing services at QualiTau (US facility)**
- **Application support**
- **Consumables & Accessories**
- **Patent & Intellectual property**
 - 29 US patents (several International)

~ 1400 SYSTEMS INSTALLED WORLD WIDE

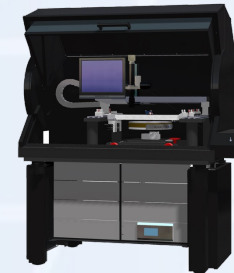
MIRA SYSTEMS



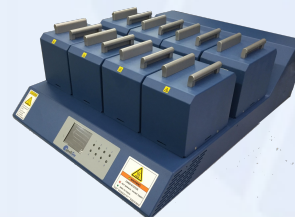
INFINITY SYSTEMS



WAFER LEVEL SYSTEMS

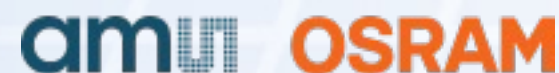
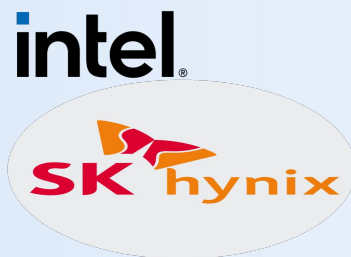
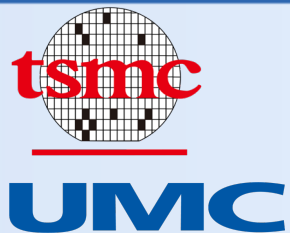


ACE SYSTEMS



Testing the Future

PARTIAL CUSTOMER LIST



Testing the Future



PROFIT & LOSS – SUMMARY (Thousands of \$US)

	<u>H1/22</u>	<u>H1/21</u>	<u>2021</u>
Total Revenues	<u>17,521</u>	<u>11,114</u>	<u>29,048</u>
Total Cost	<u>11,593</u>	<u>7,847</u>	<u>23,463</u>
Gross Income	<u>11,663</u>	<u>6,952</u>	<u>17,890</u>
Operating Income	<u>5,928</u>	<u>3,267</u>	<u>7,138</u>
Income Before Tax	<u>5,634</u>	<u>3,157</u>	<u>6,927</u>

STATEMENT OF INCOME

	<u>H1-2022</u>	<u>%</u>	<u>H1-2021</u>	<u>%</u>	<u>Y-2021</u>	<u>%</u>
REVENUES	17,521	100	11,114	100	29,048	100
COST OF SALES	5,858		4,162		11,158	
GROSS PROFIT	11,663	66.6	6,952	62.6	17,890	61.6
RESEARCH & DEVELOPMENT	2,141	12.2	2,224	20.0	4,901	16.9
SALES & MARKETING	1,597	9.1	1,169	10.5	3,082	10.6
GENERAL & ADMINISTRATION	2,006	11.4	1,634	14.7	4,111	14.1
OTHER EXPENSES (INCOME)	(9)		(1,342)		(1,342)	
OPERATING INCOME (LOSS)	5,928	33.8	3,267	29.4	7,138	24.6
EBITDA	5,822	33.2	3,459	31.1	7,317	25.2
FINANCE INCOME (EXPENSE)	(294)		(110)		----	
TAX EXPENSES (INCOME)	1,343		(308)		501	
EQUITY GAIN (LOSS)	----		----		----	
NET INCOME (LOSS)	4,291	26.5	3,465	31.2	6,426	22.1
<i>EARNING (LOSS) PER SHARE</i>	0.998		0.814		1.507	
<i>DILUTED EARNINGS PER SHARE</i>	0.941		0.736		1.443	

CASH FLOW H1-2022, H1-2021, Y-2021

	<u>30.6.2022</u>	<u>30.6.2021</u>	<u>Y-2021</u>
NET INCOME (LOSS)	4,291	3,465	6,426
ADJUSTMENTS FOR RECONCILIATION	(4,087)	(2,426)	(566)
CASH FLOW FROM (TO) OPERATION ACTIVITIES	<u>204</u>	<u>1,039</u>	<u>5,860</u>
CASH FLOW FROM (TO) INVESTMENT ACTIVITIES	(5)	(6)	(32)
CASH FLOW FROM (TO) FINANCING ACTIVITIES	(2,230)	(1,806)	(3,519)
INCREASE (DECREASE) IN CASH	<u>(2,031)</u>	<u>(773)</u>	<u>2,309</u>
CASH AT THE BEGINNING OF THE PERIOD	<u>11,855</u>	<u>9,546</u>	<u>9,546</u>
CASH AT THE END OF THE PERIOD	<u>9,824</u>	<u>8,773</u>	<u>11,855</u>

BALANCE SHEET (Thousands of \$US)

	<u>30.6.2022</u>	<u>%</u>	<u>30.6.2021</u>	<u>%</u>	<u>31.12.2021</u>	<u>%</u>
CURRENT ASSETS	29,434	92.1	22,765	86.8	26,815	90.2
LONG TERM INVESTMENTS	145		150		149	
FIXED ASSETS	776		972		922	
OPERATING LEASE RIGHT...	794		1,335		1,057	
TAX ASSETS	800		1,000		800	
TOTAL	<u>31,949</u>		<u>26,222</u>		<u>29,743</u>	
CURRENT LIABILITIES	5,492	17.2	3,668	14.0	5,583	18.8
LONG TERM LIABILITIES	364		931		652	
SHAREHOLDERS EQUITY	26,093	82.0	21,623	82.5	23,508	79.0
TOTAL	<u>31,949</u>		<u>26,222</u>		<u>29,743</u>	